

LN422YPH

Round Type

φ2.0 mm

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	90	mW
Forward current	I_F	30	mA
Pulse forward current *	I_{FP}	150	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-25 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +100	$^\circ\text{C}$

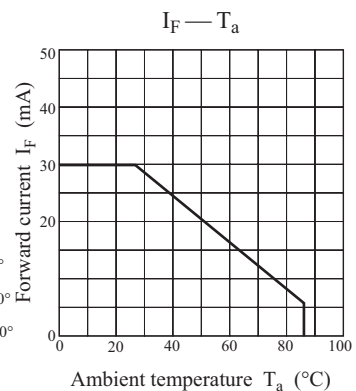
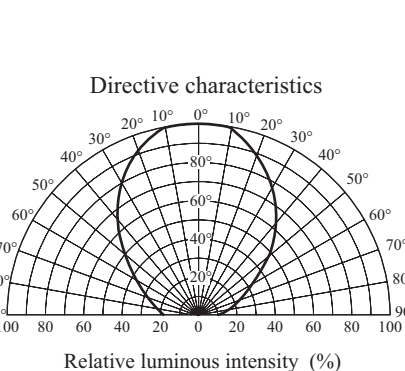
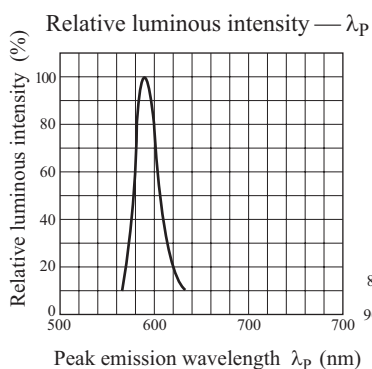
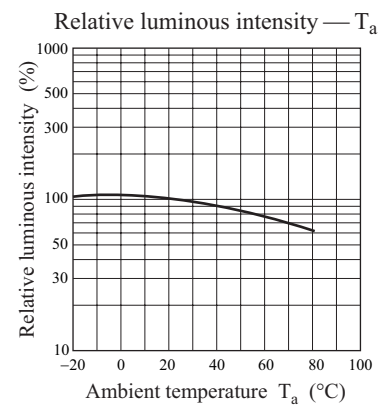
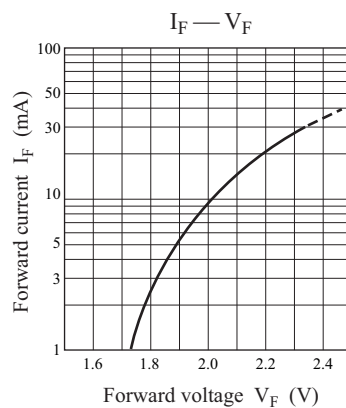
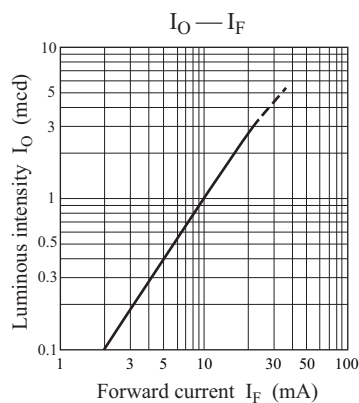
(Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

- Amber

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		1.2	2.5		mcd
Reverse current	I_R	$V_R = 4\text{ V}$			10	μA
Forward voltage	V_F	$I_F = 20\text{ mA}$		2.2	2.8	V
Peak emission wavelength	λ_p	$I_F = 20\text{ mA}$		590		nm
Spectral half band width	$\Delta\lambda$	$I_F = 20\text{ mA}$		30		nm



The technical drawing illustrates the geometry of a two-pin connector through three views:

- Front View (Left):** Shows the overall profile with a total length of 27.0 ± 1.0 . The main body has a height of 8.0 ± 0.2 . The pin section has a diameter of $\phi 2.1 \pm 0.2$ and a length of 4.6 ± 0.2 . The distance between the pins is 2.54 , with individual pin widths of 1 and 2 .
- Side View (Right):** Provides a cross-sectional view of the main body, showing an outer diameter of 2.5 ± 0.2 and an inner bore diameter of 2.4 ± 0.2 .
- Top View (Bottom):** A plan view showing the rectangular footprint of the component.

Additional dimensions include a maximum insertion force of 2.0 Max., a contact length of 0.6 , and various internal features defined by diameters like $\phi 2.0 \pm 0.2$ and lengths such as 3.5 , 4.5 ± 0.2 , and 3.85 .

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